(12) 按照专利合作条约所公布的国际申请

(19) 世界知识产权组织
国 际 局

(43) 国际公布日
2025 年 10 月 2 日 (02.10.2025)

WIPO | PCT

(10) 国际公布号
WO 2025/201034 A1

(51) 国际专利分类号:
H01L 21/687 (2006.01) *H01L 21/67* (2006.01)

(21) 国际申请号: PCT/CN2025/081751

(22) 国际申请日: 2025 年 3 月 11 日 (11.03.2025)

(25) 申请语言: 中文

(26) 公布语言: 中文

(30) 优先权:
202410362270.0 2024年3月27日 (27.03.2024) CN

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(81) 指定国(除另有指明，要求每一种可提供的国家保护): AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CV, CZ, DE, DJ, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IQ, IR, IS, IT, JM, JO, JP, KE, KG, KH, KN, KP, KR, KW, KZ, LA, LC, LK, LR, LS, LU, LY, MA, MD, MG, MK, MN, MU, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SA, SC, SD,

(54) **Title:** SUBSTRATE PROCESSING APPARATUS, PROCESSING METHOD AND BUFFER MODULE

(54) 发明名称: 基片处理装置、处理方法及缓冲模块

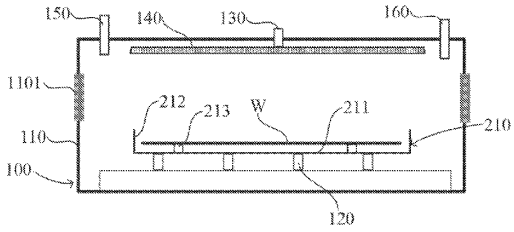


图 1

(57) **Abstract:** The present invention relates to the technical field of semiconductor devices. Disclosed are a substrate processing apparatus, a processing method and a buffer module. The substrate processing apparatus comprises a drying module and a bearing member, wherein the drying module comprises a drying cavity; the bearing member and the drying cavity are separated; the bearing member comprises a bearing portion and a blocking portion; the bearing portion is configured to bear a substrate; the blocking portion is provided on the periphery of the bearing portion; and the blocking portion is configured such that when the bearing portion bears the substrate, the height of the blocking portion is not lower than that of the substrate. The bearing member and the drying cavity are separated such that the bearing member is easier to take out from the drying cavity, and compared with the integrated design of the bearing member and the drying cavity, the height and shape of the blocking portion can be adjusted more easily.

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SE, SG, SK, SL, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UY, UZ, VC, VN, WS, ZA, ZM, ZW。

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本国际公布:

— 包括国际检索报告(条约第21条(3))。

(57) 摘要: 本发明公开了一种基片处理装置、处理方法及缓冲模块，涉及半导体设备技术领域，一种基片处理装置，包括干燥模块和承载件，所述干燥模块包括干燥腔；所述承载件与所述干燥腔可分离设置，所述承载件包括承载部和阻挡部，所述承载部用于承载基片，所述阻挡部设置于所述承载部外周，所述阻挡部被配置为：当所述承载部承载所述基片时，所述阻挡部的高度不低于所述基片的高度。承载件与干燥腔可分离设置，承载件更容易从干燥腔内取出，相比承载件与干燥腔一体化设计，更容易对阻挡部的高度及形状进行调整。